ABSTRACT

A method and device for alternately contacting two wafer-like component composite arrangements (12, 14) consisting of a plurality of cohesively designed similar components, in particular of a semiconductor wafer with a function component wafer for manufacturing electronic modules on a wafer level, in which the two component composite arrangements, each provided with contact metallizations on their opposing contact surfaces (38, 39), are brought into a coverage position with their contact metallizations to form contact pairs, in which position the contact metallizations that are to be joined together are pressed against one another, the contact metallizations being thereby contacted by exposing the rear of one of the component composite arrangements (12) to laser radiation (20), the wavelength of the laser radiation being selected as a function of the degree of absorption of the component composite arrangement exposed to laser radiation at the rear, so that a transmission of the laser radiation through the component composite arrangement exposed to the laser radiation at the rear is essentially suppressed or an absorption of the laser radiation takes place essentially in the contact metallizations of one or both component composite arrangements.

(Fig. 1)